



PATENTS
112055-0040P1
17732-38560.001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of:)
David Chong Sook Lim et al.)
Serial No.: 10/664,982)
Filed: September 17, 2003)
For: PACKAGING SYSTEM FOR)
DIE-UP CONNECTION OF A)
DIE-DOWN ORIENTED INTE-)
GRATED CIRCUIT)

Examiner: Leonardo Andujar

Art Unit: 2826

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September 23, 2005

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

SUPPLEMENTAL AMENDMENT

In response to the Office action dated 05/20/2005, please enter the following supplemental amendments: